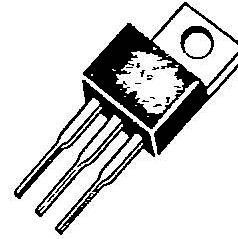


**Description**

These devices are n-channel, enhancement mode, power MOSFETs designed especially for high speed applications, such as switching power supplies, converters, AC and DC motor controls, relay and solenoid driver and high energy pulse circuits.

- Low  $R_{DS(on)}$
- $V_{GS}$  Rated at  $\pm 20V$
- Silicon Gate for Fast Switching Speeds
- $I_{DSS}$ ,  $V_{DS(on)}$ , Specified at Elevated Temperature
- Rugged
- Low Drive Requirements
- Ease of Paralleling

TO-220AB



1560010F

IRF711  
IRF712  
IRF713  
MTP2N35  
MTP2N40

**Maximum Ratings**

Symbol	Characteristic	Rating IRF710/712 MTP2N40	Rating IRF711/713 MTP2N35	Unit
$V_{DSS}$	Drain to Source Voltage <sup>1</sup>	400	350	V
$V_{DGR}$	Drain to Gate Voltage <sup>1</sup> $R_{GS}=20k \Omega$	400	350	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	$\pm 20$	V
$T_J, T_{sgt}$	Operating Junction and Storage Temperatures	-55 to +150	-55 to +150	
$T_L$	Maximum Lead Temperature for Soldering Purposes, 1/8" From Case for 5 s	275	275	

**Maximum On-State Characteristics**

		IRF710-711	IRF712-713	MTP2N35/40	Unit
$R_{DS(on)}$	Static Drain-to-Source On Resistance	3.6	5.0	5.0	$\Omega$
$I_D$	Drain Current				A
	Continuous at $T_c=25$	1.5	1.4	1.3	
	Continuous at $T_c=100$	1.0	0.9	0.8	
	Pulsed	6.0	5.0	5.0	

**Maximum On-State Characteristics**

$R_{\theta JC}$	Thermal Resistance Junction to Case	6.4	6.4	2.5	/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	80	80	80	/W
$P_D$	Total Power Dissipation at $T_c=25$	20	20	50	W

**Notes**

For information concerning connection diagram and package outline, refer to Section 7.

**Electrical Characteristics** (Tc=25 unless otherwise noted)

Symbol	Characteristic	Min	Max	Unit	Test Conditions
<b>Off Characteristics</b>					
V <sub>(BR)DSS</sub>	Drain Source Breakdown Voltage <sup>1</sup> IRF710/712/MTP2N40 IRF711/713/MTP2N35	400		V	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA
		350			
I <sub>DSS</sub>	Zero Gate Voltage Drain Current		250	μA	V <sub>DS</sub> =Rated V <sub>DSS</sub> , V <sub>GS</sub> =0V
			1000	μA	V <sub>DS</sub> =0.8 x Rated V <sub>DSS</sub> , V <sub>GS</sub> =0V, Tc=125
I <sub>GSS</sub>	Gate-Body Leakage Current		±500	μA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V
<b>On Characteristics</b>					
V <sub>GS(th)</sub>	Gate Threshold Voltage IRF710-713 MTP2N35/2N40	2.0	4.0	V	I <sub>D</sub> =250μA, V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =1mA, V <sub>DS</sub> =V <sub>GS</sub>
		2.0	4.5		
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance <sup>2</sup> IRF710/711 IRF712/713/MTP2N35/40		3.6	Ω	V <sub>GS</sub> =10V, I <sub>D</sub> =0.8A
			5.0		
V <sub>DS(on)</sub>	Drain-Source On-Voltage <sup>2</sup> MTP2N35/2N40		13	V	V <sub>GS</sub> =10V, I <sub>D</sub> =2.0A
			10	V	V <sub>GS</sub> =10V, I <sub>D</sub> =1.0A, Tc=100
g <sub>fs</sub>	Forward Transconductance	0.5		S(Ω)	V <sub>DS</sub> =10V, I <sub>D</sub> =0.8A
<b>Dynamic Characteristics</b>					
C <sub>iss</sub>	Input Capacitance		200	pF	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V f=1.0MHz
C <sub>oss</sub>	Output Capacitance		50	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance		15	pF	
<b>Switching Characteristics</b> (Tc=25, Figure 11,12) <sup>3</sup>					
t <sub>d(on)</sub>	Turn-On Delay Time		10	ns	V <sub>DD</sub> =200V, I <sub>D</sub> =0.8A V <sub>GS</sub> =10V, R <sub>GEN</sub> =50 Ω R <sub>GS</sub> =50 Ω
t <sub>r</sub>	Rise Time		20	ns	
t <sub>d(off)</sub>	Turn-Off Delay Time		10	ns	
t <sub>f</sub>	Fall Time		15	ns	
Q <sub>g</sub>	Total Gate Charge		7.5	nC	V <sub>GS</sub> =10V, I <sub>D</sub> =2.0A V <sub>DD</sub> =200V

**Electrical Characteristics (Cont.)** (Tc=25 unless otherwise noted)

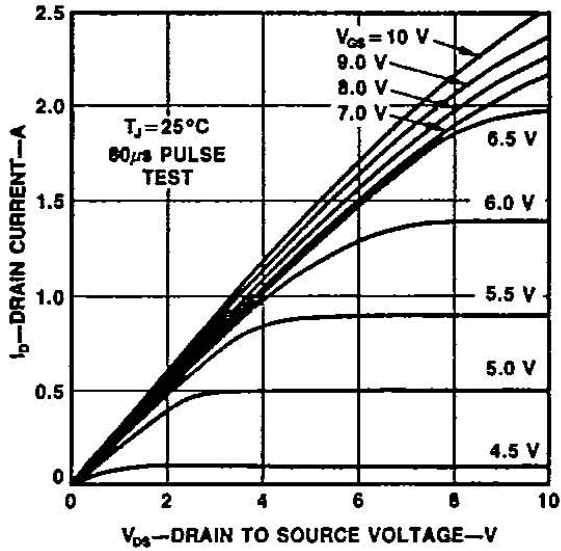
Symbol	Characteristic	Typ	Max	Unit	Test Conditions
<b>Source-Drain Diode Characteristics</b>					
V <sub>SD</sub>	Diode Forward Voltage IRF710/711 IRF712/713		1.6	V	I <sub>S</sub> =1.5A; V <sub>GS</sub> =0V
			1.5	V	I <sub>S</sub> =1.3A; V <sub>GS</sub> =0V
t <sub>rr</sub>	Reverse Recovery Time	380		ns	I <sub>S</sub> =1.5A; dI <sub>S</sub> /dt=25A/μS

**Notes**

- T<sub>J</sub>=+25 to +150
- Pulse test: Pulse width ≤ 80μs, Duty cycle ≤1%
- Switching time measurements performed on LEM TR-58 test equipment.

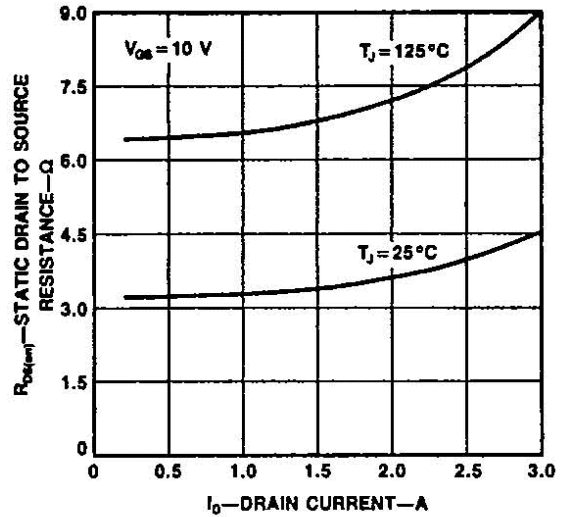
## Typical Performance Curves

Figure 1 Output Characteristic



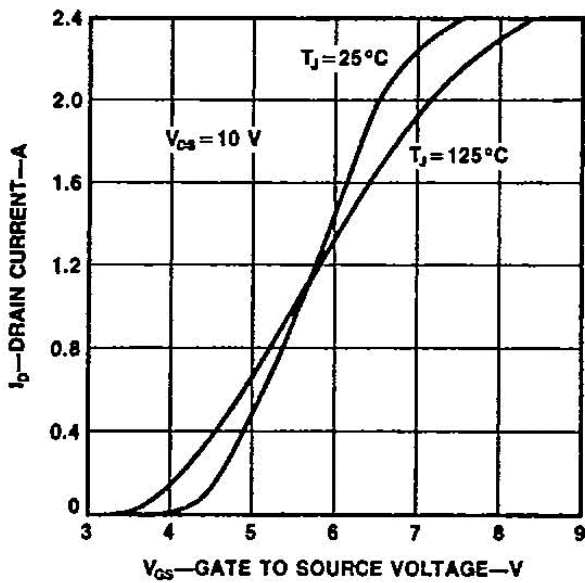
PC11120F

Figure 2 Static Drain to Source Resistance Vs Drain Current



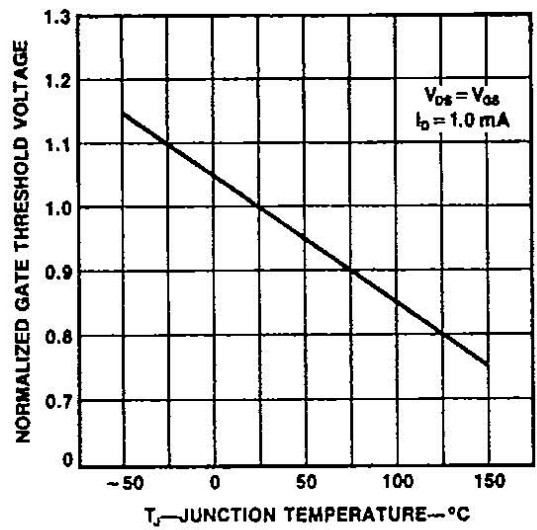
PC11130F

Figure 3 Transfer Characteristics



PC11140F

Figure 4 Temperature Variation of Gate to Source Threshold Voltage



PC09841F

Typical Performance Curves (Cont.)

Figure 5 Capacitance vs Drain to Source Voltage

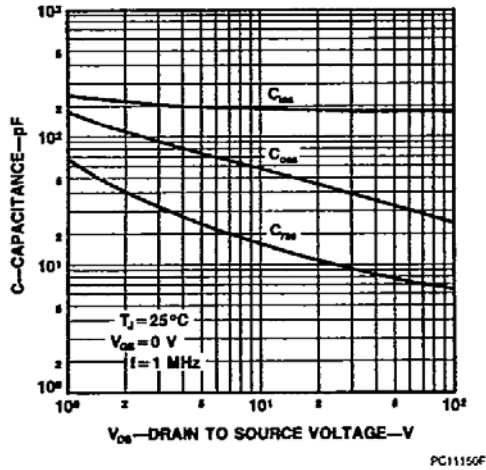


Figure 6 Gate to Source Voltage vs Total Gate Charge

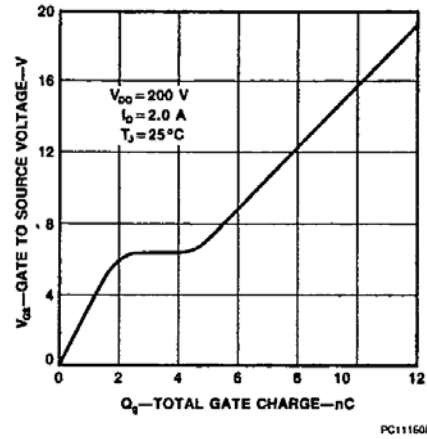


Figure 7 Forward Biased Safe Operating Area for MTP2N35/2N40

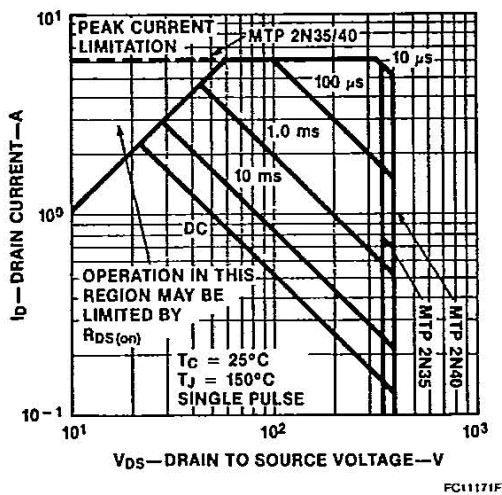


Figure 8 Transient Thermal Resistance vs Time for MTP2N35/2N40

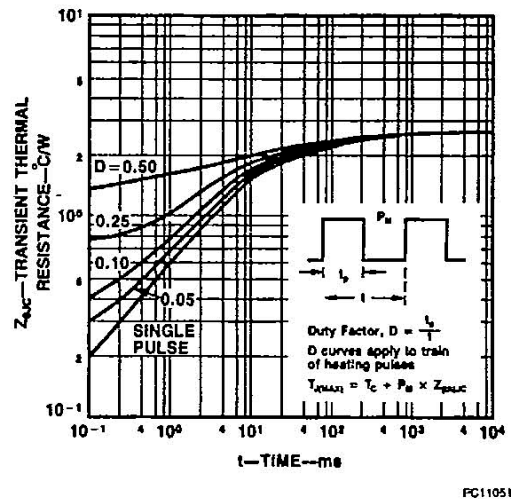


Figure 9 Forward Biased Safe Operating Area for IRF710-713

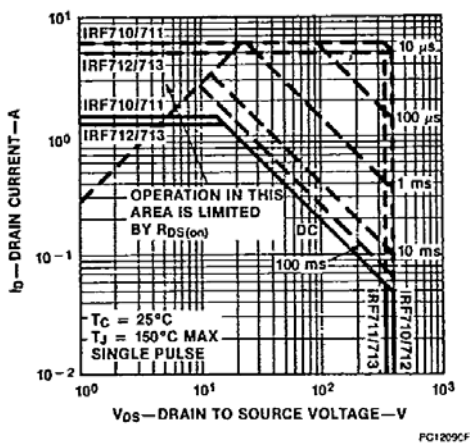
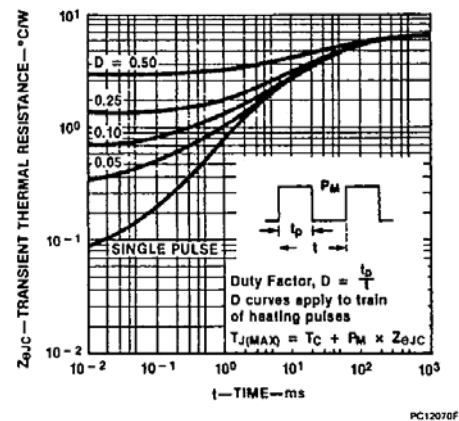


Figure 10 Transient Thermal Resistance for IRF710-713



### Typical Electrical Characteristics

Figure 11 Switching Test Circuit

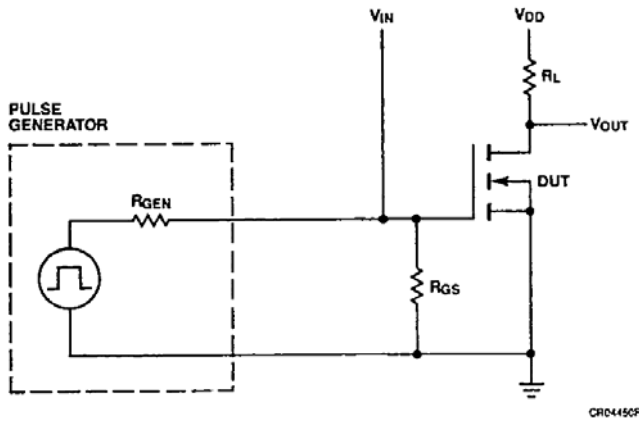


Figure 12 Switching Waveforms

